

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6701DxxxFR-G

Typical Mass: 130 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.617	Silicon	4700	7440-21-3
Leadframe	48.137	Copper	370300	7440-50-8
	0.034	Iron	300	7439-89-6
	0.014	Phosphorus	100	7723-14-0
	0.734	Silver	5600	7440-22-4
Die attach	0.070	Silver	500	7440-22-4
	0.023	Epoxy	200	—
Bonding wire	0.030	Gold	200	7440-57-5
Resin	68.760	Silica	528900	60676-86-0
	5.265	Epoxy Resin	40500	—
	4.048	Phenol Resin	31100	—
Plating	2.270	Tin	17500	7440-31-5

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."